



## Product Change Notice

Micron PCN: 31209  
 Date: 3/31/2014

<b>Type of Change:</b>	Die Shrink	
<b>Title of Change:</b>	Product die shrink transition - 25nm MLC NAND + v4.51 uC + 30nm LPDDR2 based 162b eMCP's	
<b>Description of Change:</b>	Micron is transitioning 162b eMMC+LPDDR2 MCP Product portfolio to newer process node die shrinks with improved performances in line with Market requirements. Current devices 25nm MLC NAND + v4.51 uC + 30nm LPDDR2 will transition to 20nm MLC NAND + v4.51 uC + 25nm LPDDR2	
<b>Reason for Change:</b>	Better align industry standards	
<b>Contact Information:</b>	<u>Marketing Contact</u> TAMMY KOSER-LOOSLI Micron Semiconductor Prds <a href="mailto:TMLOOSLI@MICRON.COM">TMLOOSLI@MICRON.COM</a>	<u>Engineering Contact</u> RODOLPHE SEQUEIRA Micron Semiconductor Ital <a href="mailto:RSEQUEIR@MICRON.COM">RSEQUEIR@MICRON.COM</a>

**Product Affected:** 25nm MLC NAND + v4.51 uC + 30nm LPDDR2 based 162b eMCP's

Density	Affected Micron Part Number	Replacement Part Number
4GB eMMC + 4Gb LPDDR2	MT29PZZZ4D4WKETF-18 W.6E4	MT29PZZZ4D4BKESK-18 W.94H
	MT29PZZZ4C4WKETF-18 W.6E4	Contact Factory
4GB eMMC + 8Gb LPDDR2	MT29PZZZ8D4WKFEW-18 W.6D4	MT29PZZZ8D4BKFSK-18 W.94L
8GB eMMC + 8Gb LPDDR2	MT29PZZZ8D5WKFMW-18 W.6D5	MT29PZZZ8D5BKFTF-18 W.95L

**Method of Identification:**  
 Marketing Part Number

**Micron Sites Affected:** All Sites

**Die Shrink Timeline:**

**New Shrink Size:**

Sample Available: Now  
 Qual Data Available: April 2014  
 Product Ship Date: May 2014

**Current Shrink Size:**

Last Time Buy: 9-Sep-2014  
 Last Time Ship: 5-Mar-2015

Orders placed prior to the LTB date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged.